

REMARKS

Claims 1, 3, 5, 7, 9 and 10 are pending in this application. Claim 1 is amended and claims 9 and 10 are added herein. Support for the amendments can be found at, for example, Figure 4, original claim 2 and paragraph [0050].

Claims 1-6 were rejected under 35 U.S.C. §103 over Gause et al. in view of Voroba. In addition, claims 7 and 8 were rejected under 35 U.S.C. §103 over Gause in view of Voroba and further in view of Huang et al. Applicants respectfully traverse the rejections.

As indicated in the previous Amendments, Gause is directed to unclad or metal clad laminates constructed by sandwiching a resin impregnated core of paper between epoxy resin impregnated woven glass fabric sheets. Gause teaches that metal foil may be bonded directly to one or both of the outer woven glass layers during the fabrication of the laminate.

Gause does not teach or suggest a laminate in which copper foils are directly laminated to a resin impregnated paper base. In contrast, in Gause, the metal foils are bonded to an outer woven glass layer, which the Patent Office has equated to the claimed resist.

Neither Voroba nor Huang overcome the deficiencies of Gause. In particular, neither of these references teach or suggest a laminate in which copper foils are directly laminated to a resin impregnated paper base.

Gause, Voroba and Huang, alone or as combined, fail to teach or suggest all of the features of claim 1. Therefore, the rejections under 35 U.S.C. §103 over these references should be reconsidered and withdrawn.

Claims 1-4 were rejected under 35 U.S.C. §103 over Nomura in view of Voroba. In addition, claims 7 and 8 were rejected under 35 U.S.C. §103 over Nomura in view of Voroba and further in view of Huang. Applicants respectfully traverse the rejections.

As indicated in the previous Amendments, Nomura is directed to a base board

comprising at least one sheet of prepreg comprising a thermosetting resin as an impregnant and a layer comprising a composition of a semi-cured thermosetting resin and a nitrile rubber on one or both sides of the prepreg layer. In addition, Nomura teaches the use of this base board for printing circuits prepared by the additive process. In the additive process, metal is plated on the base board, masking ink is plated on the metal layer to form the circuit pattern, metal is plated in the areas not plated by the masking ink, and the masking ink layer is then removed.

Nomura does not teach or suggest a laminate in which copper foils are directly laminated to a resin impregnated paper base. In contrast, in Nomura, metal is plated on the layer comprising a composition of a semi-cured thermosetting resin and a nitrile rubber, which the Patent Office has equated to the claimed resist.

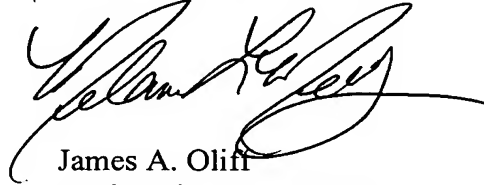
Neither Voroba nor Huang overcome the deficiencies of Nomura. In particular, neither Voroba nor Huang teach or suggest a laminate in which copper foils are directly laminated to a resin impregnated paper base.

Nomura, Voroba and Huang, alone or as combined, fail to teach or suggest all of the features of claim 1. Therefore, the rejections under 35 U.S.C. §103 over these references should be reconsidered and withdrawn.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1, 3, 5, 7, 9 and 10 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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